



**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	1/8

## 1. Scope

This specification applied to the products of Lead-Free current sensing resistor of metal plate for Lead-Free RLF series manufactured by TA-I TECHNOLOGY CO.,LTD.

## 2. Type Designation

RLF12	F	E	E	R001
Series No.	Tolerance	Packaging	Power	Resistance
12 : 1225 (F=4-Wire)	F= $\pm 1\%$ G= $\pm 2\%$ J= $\pm 5\%$	E= Embossed	C=1W E= 2W	e.g. R001=1m $\Omega$

## 3. Features

Type	RLF 12
Size	1225
Power Rating	2W
Resistance Value	1m $\Omega$ ~3m $\Omega$
Operation Temperature Range	-55°C~+170°C
TCR	$\pm 100$ ppm/°C
Tolerance	$\pm 1\%$ 、 $\pm 2\%$ 、 $\pm 5\%$
Insulation Resistance	Over 100M $\Omega$
Maximum Working Voltage(V)	$(P \cdot R)^{1/2}$

\*Note : The specifications and characteristics of this product are not suitable for series and parallel use.



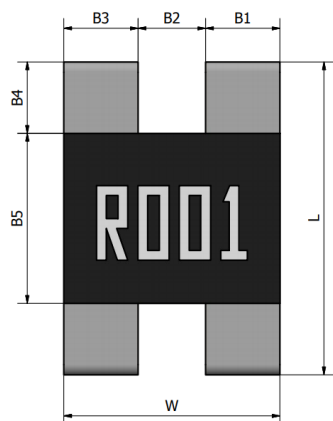
**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No TRLF-120S001C

Issued date 2024/8/8

page 2/8

#### 4. Construction and Dimension



Sn: Matte Sn

Ni/Sn Plating

Over-Coat



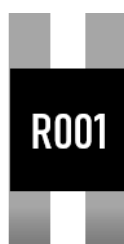
Metal Alloy Construction

Series	L	W	t	B1	B2	B3	B4	B5
RLF12	6.40 ±0.20	3.20 ±0.20	0.70 ±0.20	0.95 ±0.20	1.25 ±0.20	0.95 ±0.20	2.2 ±0.20	2.1 ±0.20

UNIT: mm

#### Marking

The marking pattern is as follows.



Resistance value is expressed by 4 digits.

E.G.:

R001 = 0.001Ω = 1mΩ

R002 = 0.002Ω = 2mΩ



**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No

TRLF-120S001C

Issued date

2024/8/8

page

3/8

## 5. Reliability Tests

Test Items	Reference	Condition of Test	Test Limits
Temperature Coefficient of Resistance	IEC60115-1 4.8	+25 ~ 125°C	Refer 4.0
High Temperature Exposure (Storage)	AEC-Q200-REV E-Test 3 MIL-STD202 Method 108	T=170°C,1000hrs, Measurement at 24hrs after test conclusion.	$< \pm(1\%+0.0005\Omega)$
Temperature Cycling	AEC-Q200-REV E-Test 4 JESD22 Method JA-104	1000Cycle (-55°C to 155°C), Measurement at 24hrs after test conclusion.	$< \pm(1\%+0.0005\Omega)$
Short time overload	IEC60115-1 4.13	2.5 X rated power for 5s.	$< \pm(1\%+0.0005\Omega)$
Biased Humidity	AEC-Q200-REV E-Test 7 MIL-STD-202 Method 103	10% Rated power at 85°C, RH:85% ,1000Hrs, Measurement at 24hrs after test conclusion.	$< \pm(1\%+0.0005\Omega)$
Operation life	AEC-Q200-REV E-Test 8 MIL-STD-202 Method 108	1000 hours TA=70°C at 100% rated power. 90min ON and 30 min OFF. Measurement at 24±4 hours after test conclusion.	$< \pm(2\%+0.0005\Omega)$
External Visual	AEC-Q200-REV E-Test 9 MIL-STD-883 Method 2009	Electrical test not required. Inspect device construction, marking and workmanship.	
Physical Dimension	AEC-Q200-REV E-Test 10 JESD22 Method JB-100	Verify physical dimensions to the applicable device detail specification. Note: User(s) and Suppliers spec. Electrical test not required.	
Resistance to Solvents	AEC-Q200-REV E-Test 12 MIL-STD-202 Method 215	a: Isopropyl Alcohol : Mineral Spirits = 1 : 3 b: Terpene Defluxer c: Deionized water : Propylene Glycol Monomethyl Ether : monoethanolamine = 42 : 1 : 1	Marking and protective layer cannot be detached
Resistance to Soldering Heat	AEC-Q200-REV E-Test 15 MIL-STD-202 Method 210	T=260+/-5°C solder,10+/-1 sec dwell.	$< \pm(0.5\%+0.0005\Omega)$
Mechanical Shock	AEC-Q200-REV E-Test 13 MIL-STD-202 Method 213	100g's, Normal duration is 6ms, half sine shock pulse.	$< \pm(0.5\%+0.0005\Omega)$
Resistance to vibration	AEC-Q200-REV E-Test 14 MIL-STD-202 Method 204	5g's for 20min.12cycles, 10-2000Hz.	$< \pm(0.5\%+0.0005\Omega)$
Board Flex	AEC-Q200-REV E-Test 21 AEC-Q200-005	Min 2mm deflection ,60sec.	$< \pm(0.5\%+0.0005\Omega)$
Flammability	AEC-Q200-REV E-Test 20 UL-94	V-0 or V-1 are acceptable, Electrical test not required.	V-0
ESD	AEC-Q200-REV E-Test 17 AEC-Q200-002 or ISO/DIS 10605	verify the voltage setting at 500V.	$< \pm(1\%+0.0005\Omega)$
Solderability	AEC-Q200-REV E-Test 18 J-STD-002	aging 4 hours at 155 °C dry heat Lead-free solder bath at 235±3 °C Dipping time: 3±0.5 seconds.	> 95% area covered with tin

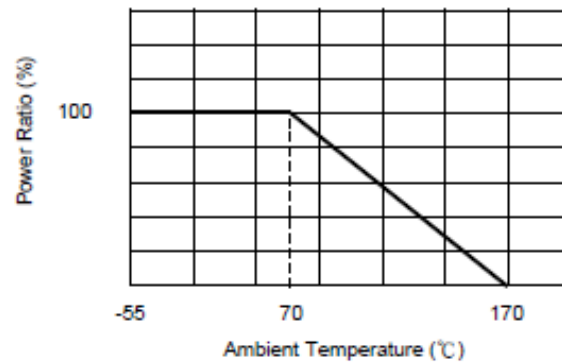


**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	4/8

Terminal Strength (SMD)	AEC-Q200-REV E-Test 22 AEC-Q200-006	Force of 1.8kg for 60 seconds. Remarks: 0201-NA	< ±(2%+0.0005Ω)
Low Temperature Storage	EC60115-1 4.23.4 JIS C 5201-1 4.23.4	-55°C, 1000hrs	< ±(1%+0.0005Ω)

### 5.1 Derating Curve



### 5.2 Rated Current

The rated current is calculated by the following formula:

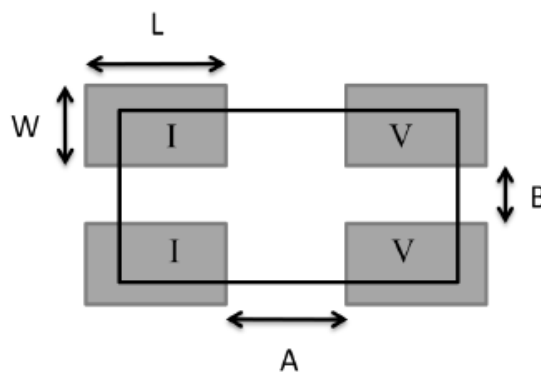
$$I = \sqrt{P \div R}$$

I: Rated Current (A)

P: Rated Power (W)

R: Resistance Value (Ω)

### 6. Recommended Solder Pad Dimension



Series	Resistance (mΩ)	A	B	L	W
RLF12	1~3	2.3±0.1	1.4±0.1	2.6±0.1	1.5±0.1

Note: \*The copper foil minimum thickness of PCB needs 3 oz

Unit: mm



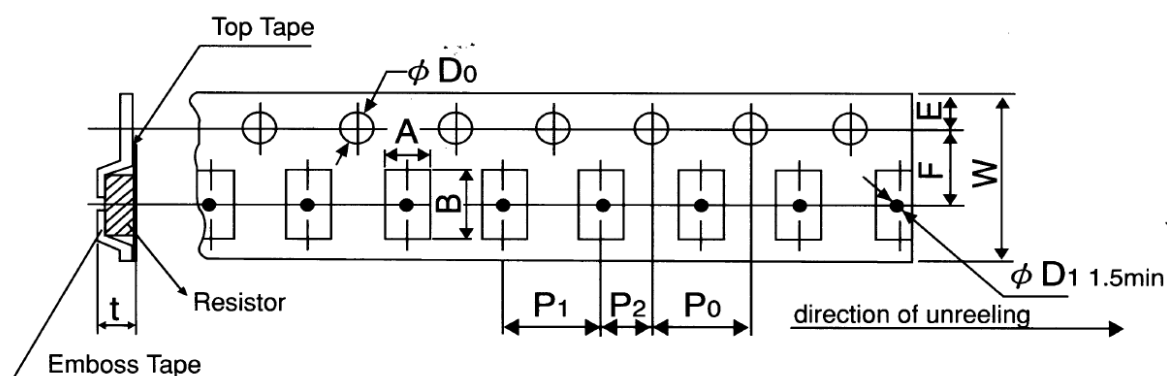
**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	5/8

## 7. Number of Package

Series	RLF12
Pieces	4000

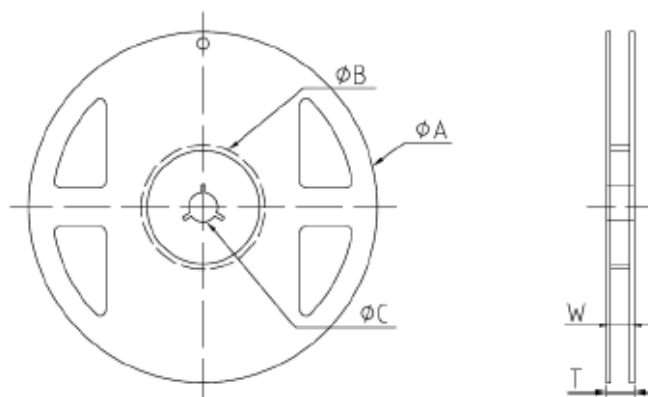
## 8. Packaging



Packing	Type	A	B	W	F	E	P1	P2	P0	ψD0	t
Emboss	RLF12	3.60	6.90	12.0	5.50	1.75	4.00	2.00	4.00	1.5	1.2
Tolerance		±0.20	±0.20	±0.20	±0.05	±0.10	±0.10	±0.10	±0.10	±0.10	±0.15

Unit: mm

## 9. Reel Specification



Series	ϕ A	ϕ B	ϕ C	W	T
RLF12	178.0 ±2.0	60.0 ±1.0	13.0 ±1.0	13.0 ±1.0	15.5±1.0

Unit: mm

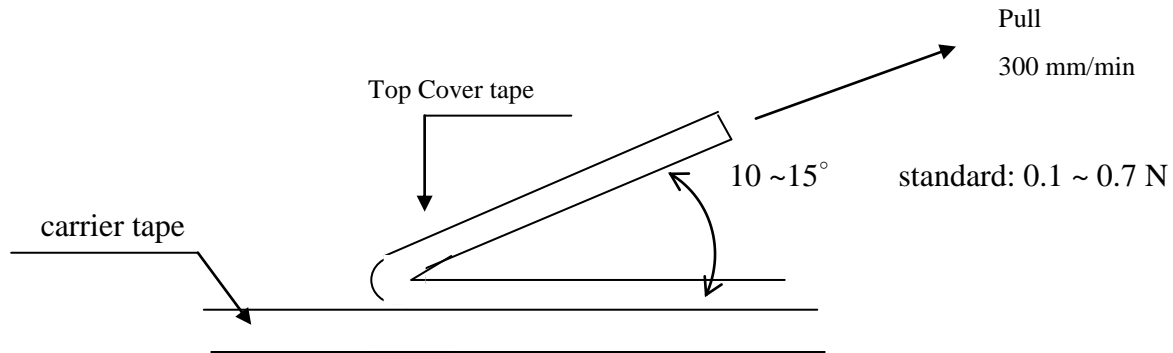


**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	6/8

### 10. Peeling Strength of Top Cover Tape

Test Condition: 0.1 to 0.7 N at a peel-off speed of 300 mm / min.



### 11. Storage Conditions

Temperature: 5°C~35°C, Humidity:40%~75%  
MSL level 1

### 12. Shelf Life

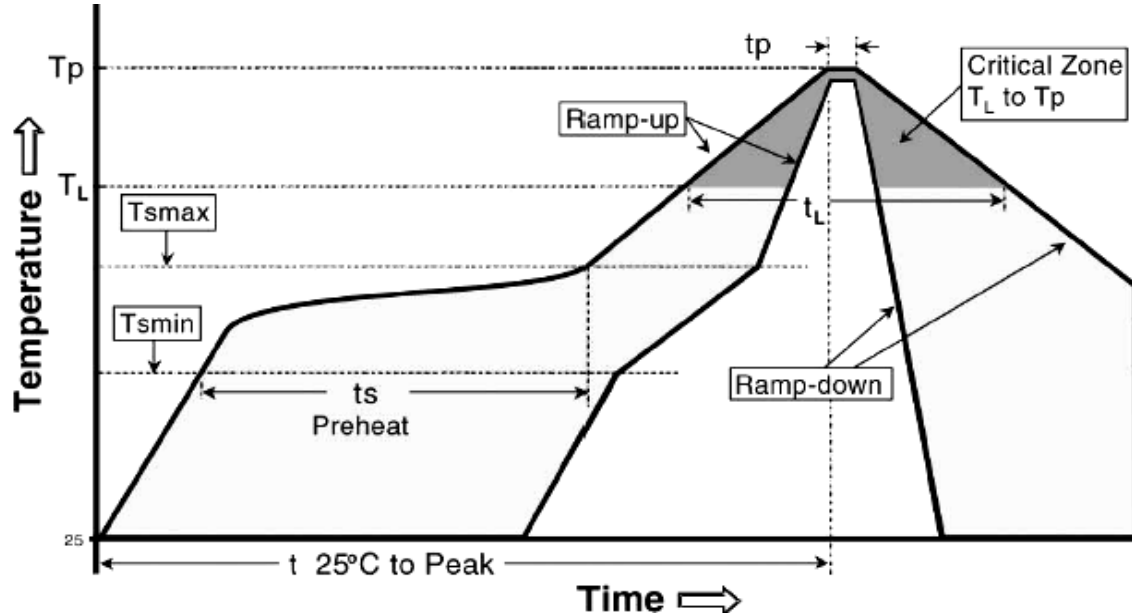
2 years from manufacturing date.



**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	7/8

**13. Recommend IR – Reflow profile** (solder: Sn96.5 / Ag3 / Cu0.5)



**Allowed Re-flow times: 3 times**

**Remark: To avoid discoloration phenomena of chip on terminal electrodes, please use N2 Re-flow furnace.**

**Iron Solder: 350±10°C, 3+1/-0 sec, 1 time**

Profile Feature	Lead (Pb)-Free Assembly
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3°C / second max.
Preheat - Temperature Min (T <sub>smin</sub> ) - Temperature Max (T <sub>smax</sub> ) - Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	150°C 200°C 60 -120 seconds
Time maintained above: - Temperature (T <sub>L</sub> ) - Time (T <sub>L</sub> )	217°C 60-150 seconds
Peak Temperature (T <sub>p</sub> )	260°C
Time within $\begin{matrix} +0 \\ -5 \end{matrix}$ °C of actual Peak Temperature (t <sub>p</sub> ) <sup>2</sup>	10 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8minutes max.

**14. ECN**



**Lead-Free Current Sensing Resistors**  
**RLF Series**  
**(Halogen-Free)**  
**AEC-Q 200-Ver E qualified**

Document No	TRLF-120S001C
Issued date	2024/8/8
page	8/8

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.

**15. Manufacturing Country & City**

TA-I TECHNOLOGY CO., LTD. (Taiwan– Tao Yuan)

Tel: (+886) 3-3246169 Fax: (+886) 3-3246167

**Associated companies**

(1)TA-I TECHNOLOGY (SU ZHOU) CO., LTD. (China – Su Zhou)

Tel :(+86) 512-63457879 Fax: (+86) 512-63457869

(2)TA-I TECHNOLOGY ELECTRONIC (DONGGUAN) CO., LTD. (China –Dongguan)

Tel : (+86) 769-8339-4790~3 Fax : (+86) 769-8339-4794

(3) FORTUNE TASK ENTERPRISES LIMITED (China – Dongguan)

Tel : (+86) 769-8339-4790~3 Fax : (+86) 769-8339-4794

(4)TAI OHM ELECTRONICS (M) SDN. BHD. (Malaysia –Penang)

Tel: (+60)4- 3900480 Fax: (+60)4-3901481